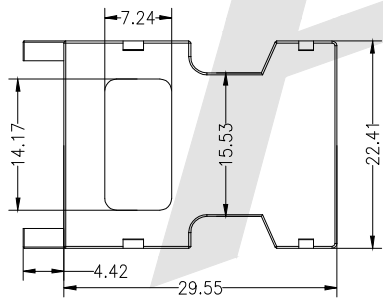
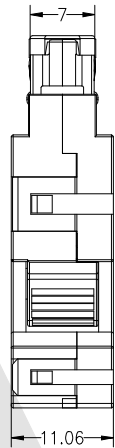
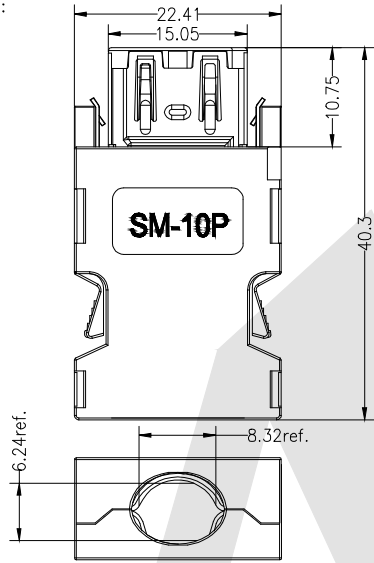


HSF

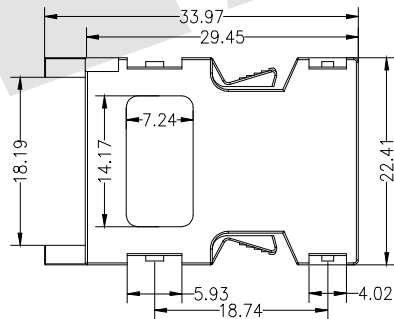


ROHS

成品组装图:
(Assemble)



塑胶下盖(bottom shell plastic)



塑胶上盖(up shell plastic)

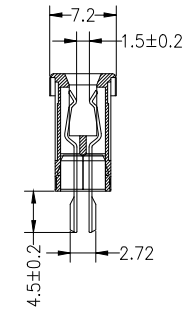
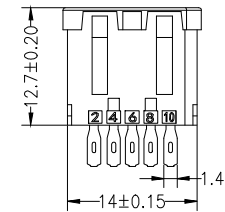
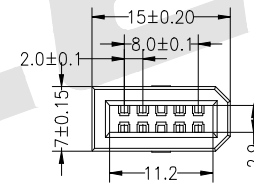
SPECIFICATIONS

Rated Current:1.0Amp
 Contact Resistance:20mΩ Max
 Withstand Voltage:500V AC/DC
 Insulation Resistance:1000MΩ Min
 Operation Temperature:-40°C to +105°C
 Contact Material:Phosphor Bronze
 Contact Plating:Au Over Ni
 Insulator Material:Polyester(UL94V-0)
 Standard:PA6T
 Max.Processing Temp: 230°C for 30-60 seconds
 (260°C for 10 seconds)

Ordering Code

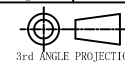
IEMS03 - X - X - X - X - X
 ① ② ③ ④ ⑤ ⑥

- ① Series No:
- ② Shell Material:
B:Brass I:Iron
S:stainless steel
- ③ Insulator Material:
P:PBT+30%GF
L:LCP
- ④ Contact Material:
B:Brass
P:phosphor copper
- ⑤ Contact Plating
G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold
- ⑥ Packing
A:Tray
B:Bag
C:Tube
D:Tape Reel



Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
 DRAW ZLA DATE 25/04/2022
 CHECK BobYang DATE 25/04/2022



Antenk ANTEK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE:
 IEEE1394 SMT Male 10P with shell assemble

DRAWING NO: IEMS03-X-X-X-X-X

PRODUCT NO: IEMS03-X-X-X-X-X

REV DESCRIPTION

DATE

1 2 3 4 5 6 7 8